SN74ALVCH16841 20-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

SCES043E-JULY 1995-REVISED SEPTEMBER 2004

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

DESCRIPTION

This 20-bit bus-interface D-type latch is designed for 1.65-V to 3.6-V $V_{\rm CC}$ operation.

The SN74ALVCH16841 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, unidirectional bus drivers, and working registers.

The SN74ALVCH16841 can be used as two 10-bit latches or one 20-bit latch. The 20 latches are transparent D-type latches. The device has noninverting data (D) inputs and provides true data at its outputs. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the D inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

DGG OR DL PACKAGE (TOP VIEW)

1 0E		1	\cup	56		1LE
1Q1	D	2		55	1	1D1
1Q2		3		54		1D2
GND		4		53		GND
1Q3		5		52		1D3
1Q4		6		51		1D4
V_{CC}		7		50		V_{CC}
1Q5		8		49	1	1D5
1Q6		9		48	0	1D6
1Q7		10		47		1D7
GND		11		46	0	GND
1Q8		12		45		1D8
1Q9		13		44	р	1D9
1Q10		14		43		1D10
2Q1		15		42		2D1
2Q2		16		41		2D2
2Q3		17		40		2D3
GND		18		39		GND
2Q4		19		38		2D4
2Q5		20		37	1	2D5
2Q6		21		36		2D6
V_{CC}		22		35		V_{CC}
2Q7		23		34	þ	2D7
2Q8		24		33		2D8
GND		25		32		GND
2Q9		26		31		2D9
2Q10	ď	27		30		2D10
2 OE	q	28		29		2LE
					•	

A buffered output-enable ($1\overline{OE}$ or $2\overline{OE}$) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

 $\overline{\text{OE}}$ does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16841 is characterized for operation from -40°C to 85°C.



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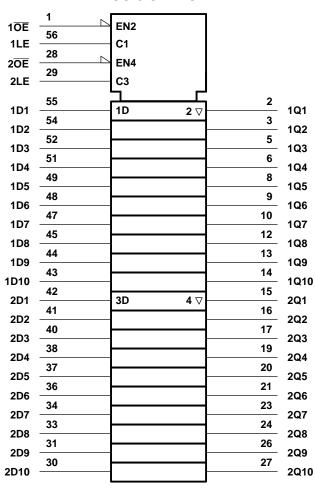
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FUNCTION TABLE (each 10-bit latch)

	INPUTS		OUTPUT
ŌĒ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	X	X	Z

LOGIC SYMBOL(1)

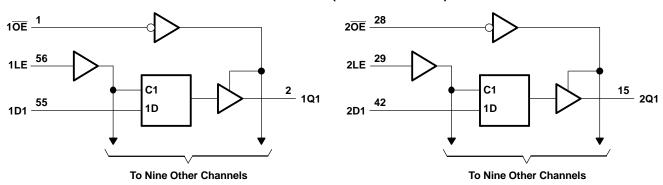


⁽¹⁾ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.





LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0	-50		mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GN	D		±100	mA
0	Dealer at the world in a dealer (4)	DGG package		81	0000
θ_{JA}	Package thermal impedance (4)	DL package	74		°C/W
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51.

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RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		8.0	
V _I	Input voltage		0	V _{CC}	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
	High level output ourrent	$V_{CC} = 2.3 \text{ V}$		-12	A
I _{OH}	High-level output current	$V_{CC} = 2.7 V$		-12	mA
		$V_{CC} = 3 V$		-24	
		V _{CC} = 1.65 V		4	
	Low-level output current	$V_{CC} = 2.3 \text{ V}$		12	mA
I _{OL}	Low-level output current	$V_{CC} = 2.7 V$		12	ША
		$V_{CC} = 3 V$		24	
Δt/Δν	Input transition rise or fall rate	·		10	ns/V
T _A	Operating free-air temperature		-40	85	°C

⁽¹⁾ All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP(1) MAX	UNIT				
	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2					
	I _{OH} = -4 mA	1.65 V	1.2					
	I _{OH} = -6 mA	2.3 V	2					
V_{OH}		2.3 V	1.7	V				
	I _{OH} = -12 mA	2.7 V	2.2					
		3 V	2.4					
	I _{OH} = -24 mA	3 V	2					
	I _{OL} = 100 μA	1.65 V to 3.6 V	0.2					
	I _{OL} = 4 mA	1.65 V	0.45					
W	I _{OL} = 6 mA	2.3 V	0.4					
V_{OL}	10	2.3 V	0.7	V				
	I _{OL} = 12 mA	2.7 V	0.4					
	I _{OL} = 24 mA	3 V	0.55					
I _I	$V_I = V_{CC}$ or GND	3.6 V	±5	μΑ				
	V _I = 0.58 V	1.65 V	25					
	V _I = 1.07 V	1.65 V	-25					
	V _I = 0.7 V	2.3 V	45	ļ				
I _{I(hold)}	V _I = 1.7 V	2.3 V	-45	μΑ				
, ,	V _I = 0.8 V	3 V	75					
	V _I = 2 V	3 V	-75					
	$V_1 = 0 \text{ to } 3.6 \text{ V}^{(2)}$	3.6 V	±500					
l _{oz}	$V_O = V_{CC}$ or GND	3.6 V	±10	μΑ				
I _{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	40	μΑ				
ΔI_{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V	750	μΑ				
Control inputs		0.01/	4.5	pF				
C _i Data inputs	$V_{I} = V_{CC}$ or GND	3.3 V	6.5					
C _o Outputs	$V_O = V_{CC}$ or GND	3.3 V	7	pF				

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high or low	(1)		3.3		3.3		3.3		ns
t_{su}	Setup time, data before LE↑	(1)		0.9		0.7		1.1		ns
t _h	Hold time, data after LE↑	(1)		1.2		1.5		1.1		ns

⁽¹⁾ This information was not available at the time of publication.

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V_{CC} = 2.5 V \pm 0.2 V		V _{CC} = 2.7 V		V _{CC} = 1 ± 0.3	UNIT	
	(INPUT)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
4	D	Q	(1)	1	5		4.7	1.2	3.9	20
^L pd	LE	Q	(1)	1	5.6		5.1	1	4.3	ns
t _{en}	ŌĒ	Q	(1)	1	6.2		6	1	4.9	ns
t _{dis}	ŌĒ	Q	(1)	1.1	5.3		4.3	1.3	4.1	ns

⁽¹⁾ This information was not available at the time of publication.

OPERATING CHARACTERISTICS

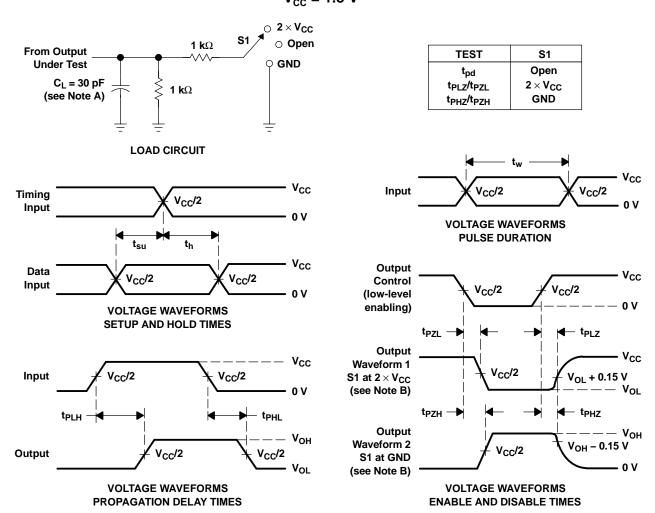
 $T_A = 25^{\circ}C$

	PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
<u> </u>	Power dissipation Outputs enabled		C 50 pF f 10 MHz	(1)	12	20	, C
C _{pd}	capacitance	Outputs disabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	(1)	1	3	pF

⁽¹⁾ This information was not available at the time of publication.



PARAMETER MEASUREMENT INFORMATION $V_{cc} = 1.8 \text{ V}$



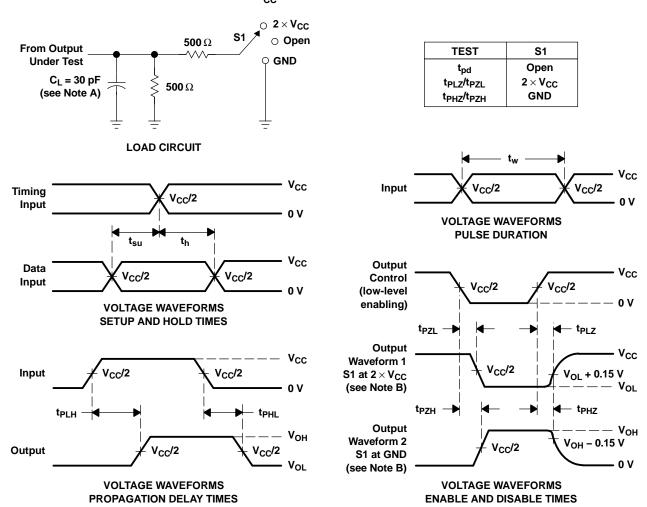
NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{Pl 7} and t_{PH7} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V



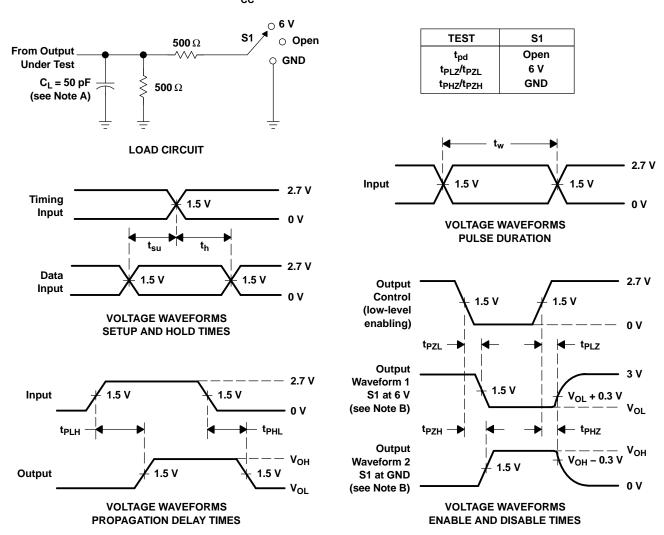
NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZI} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 3. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCH16841DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16841DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16841DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16841DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16841DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16841DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16841DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16841DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ALVCH16841DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16841DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ALVCH16841DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

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